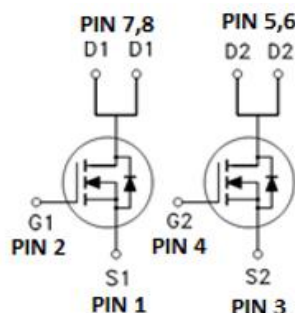


Dual N-Channel Logic Level Enhancement Mode Field Effect Transistor

•Product Summary:

	N-CH
BVDSS	30V
$R_{DS(on)} (MAX.) @ V_{GS}=10V$	12.0mΩ
$R_{DS(on)} (MAX.) @ V_{GS}=4.5V$	19.0mΩ
$I_D @ T_C=25^{\circ}C$	28.0A
$I_D @ T_A=25^{\circ}C$	10.0A

• Pin Description:



Dual N Channel MOSFET

UIS, Rg 100% Tested

Pb-Free Lead Plating & Halogen Free

•ABSOLUTE MAXIMUM RATINGS ($T_C = 25^{\circ}C$ Unless Otherwise Noted)



PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNIT
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current	$T_C = 25^{\circ}C$	I_D	28	A
	$T_C = 100^{\circ}C$		18	
Continuous Drain Current	$T_A = 25^{\circ}C$	I_D	10	
	$T_A = 70^{\circ}C$		8	
Pulsed Drain Current ¹		I_{DM}	112	
Avalanche Current		I_{AS}	30	mJ
Avalanche Energy	$L = 0.1mH$	EAS	45.0	
Repetitive Avalanche Energy ²	$L = 0.05mH$	EAR	22.5	W
Power Dissipation	$T_C = 25^{\circ}C$	P_D	16.7	
	$T_C = 100^{\circ}C$		6.7	W
Power Dissipation	$T_A = 25^{\circ}C$	P_D	2.3	
	$T_A = 70^{\circ}C$		1.5	°C
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150	

•THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Case	$R_{\theta JC}$		7.5	°C/W
Junction-to-Ambient ³	$R_{\theta JA}$		55	

¹Pulse width limited by maximum junction temperature.

²Duty cycle < 1%

³55°C / W when mounted on a 1 in² pad of 2 oz copper.

⁴Guarantee by Engineering test

▪ ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage ⁴	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250uA	30			V
Gate Threshold Voltage ⁴	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250uA	1	1.6	3	
Gate-Body Leakage ⁴	I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V			±100	nA
Zero Gate Voltage Drain Current ⁴	I _{DSS}	V _{DS} = 24V, V _{GS} = 0V			1	uA
		V _{DS} =20V, V _{GS} =0V, T _J = 125 °C			25	
On-State Drain Current ¹	I _{D(ON)}	V _{DS} = 10V, V _{GS} = 10V	28			A
Drain-Source On-State Resistance ^{1,4}	R _{DS(ON)}	V _{GS} = 10V, I _D = 10A		10	12	mΩ
		V _{GS} = 4.5V, I _D = 6A		16	19	
DYNAMIC						
Input Capacitance ⁵	C _{iss}	V _{GS} = 0V, V _{DS} = 15V, f = 1MHz		720		pF
Output Capacitance ⁵	C _{OSS}			136		
Reverse Transfer Capacitance ⁵	C _{rss}			81		
Gate Resistance ^{4,5}	R _g	f = 1MHz		1.0		Ω
Total Gate Charge ^{1,2,5}	Q _g (V _{GS} =10V)	V _{DS} = 15V, V _{GS} = 10V, I _D = 10A		13.9		nC
	Q _g (V _{GS} =4.5V)			7.1		
Gate-Source Charge ^{1,2,5}	Q _{gs}			2.2		
Gate-Drain Charge ^{1,2,5}	Q _{gd}			3.7		
Turn-On Delay Time ^{1,2,5}	t _{d(on)}	V _{DS} = 15V, V _{GS} = 10V, I _D = 5A , R _g = 6Ω		6.1		nS
Rise Time ^{1,2,5}	t _r			8.0		
Turn-Off Delay Time ^{1,2,5}	t _{d(off)}			12.9		
Fall Time ^{1,2,5}	t _f			1.8		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS						
Continuous Current	I _S				28	A
Pulsed Current ³	I _{SM}				112	
Forward Voltage ^{1,4}	V _{SD}	I _F = 10A, V _{GS} = 0V			1.2	V
Reverse Recovery Time ⁵	t _{rr}	I _F = 10A, dI _F /dt = 100A / uS		9.1		nS
Reverse Recovery Charge ⁵	Q _{rr}			3.1		nC

¹Pulse test : Pulse Width $\leq 300 \mu\text{sec}$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

³Pulse width limited by maximum junction temperature.

⁴Guarantee by FT test Item

⁵Guarantee by Engineering test

EMC will review datasheet by quarter, and update new version.



■ TYPICAL CHARACTERISTICS

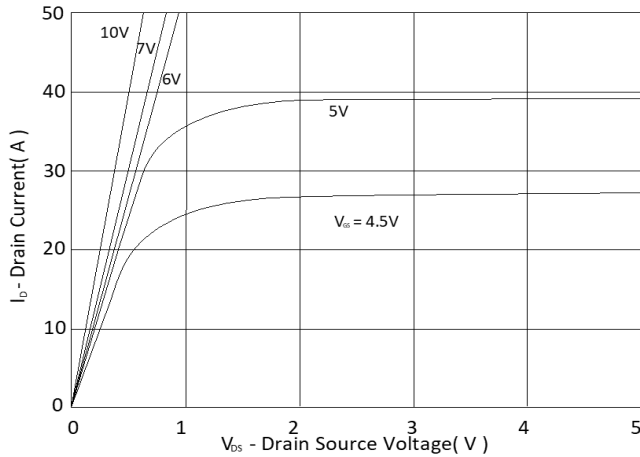


Fig.1 Typical Output Characteristics

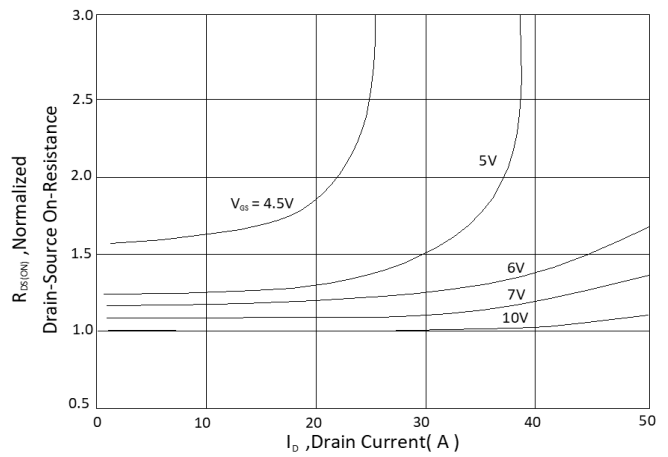


Fig.2 On-Resistance Variation with Drain Current and Gate Voltage

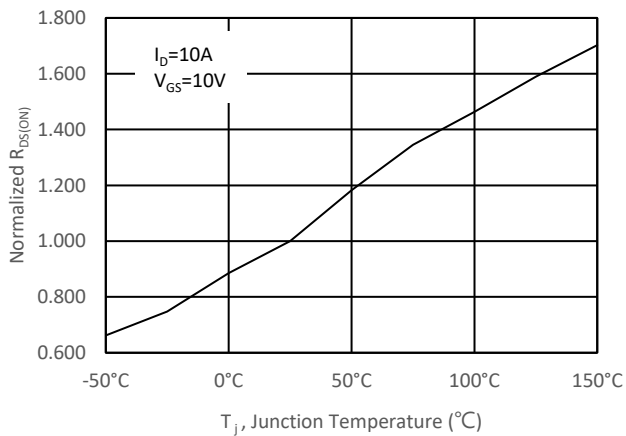


Fig.3 Normalized On-Resistance v.s. Junction Temperature

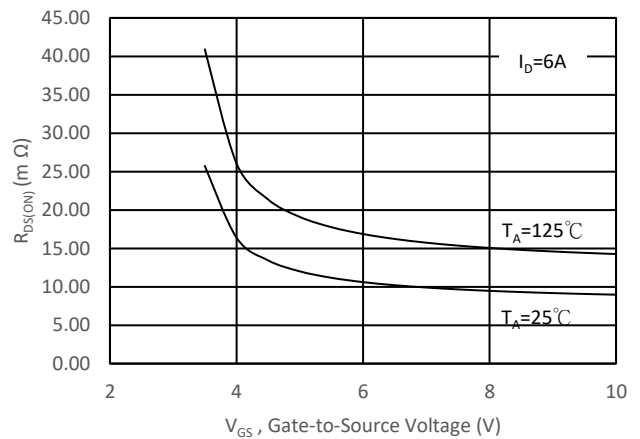


Fig.4 On-Resistance v.s. Gate Voltage

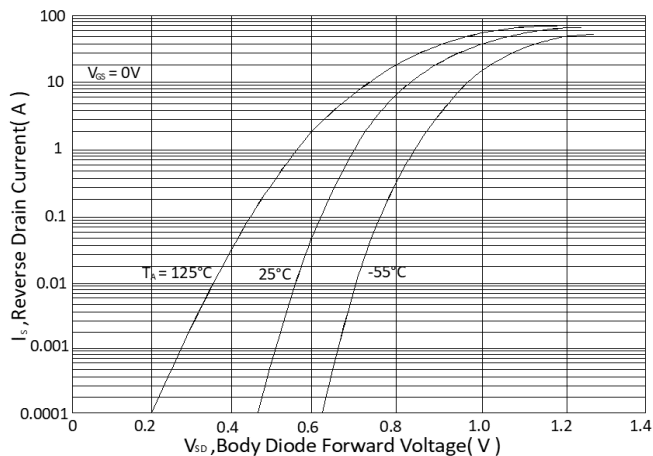


Fig.5 Forward Characteristic of Reverse Diode

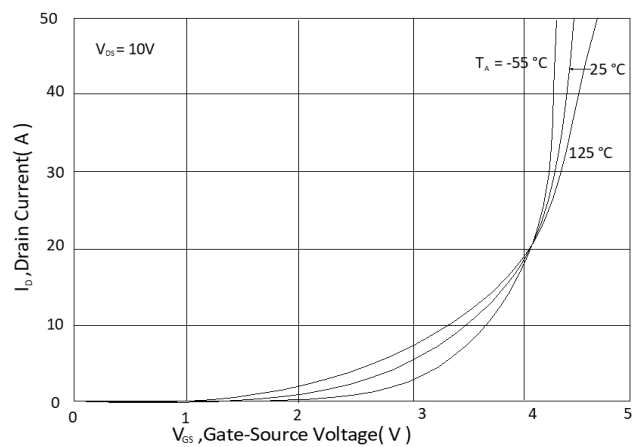


Fig.6 Transfer Characteristics

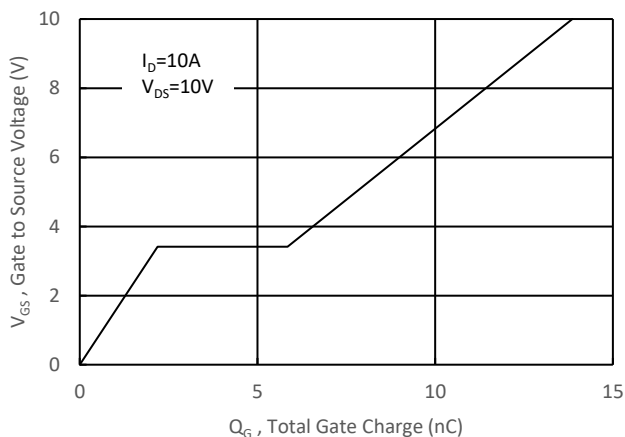


Fig.7 Gate Charge Characteristics

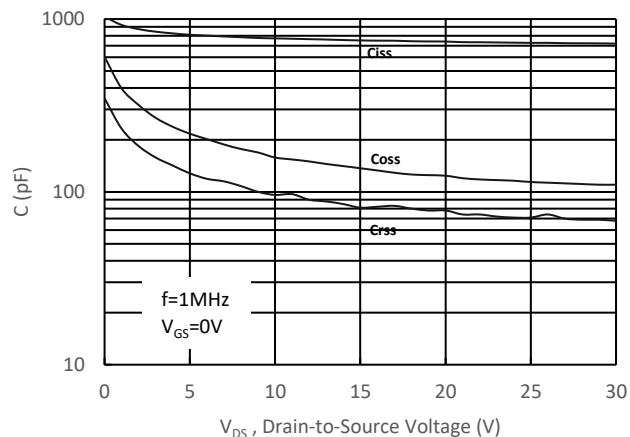


Fig.8 Typical Capacitance Characteristics

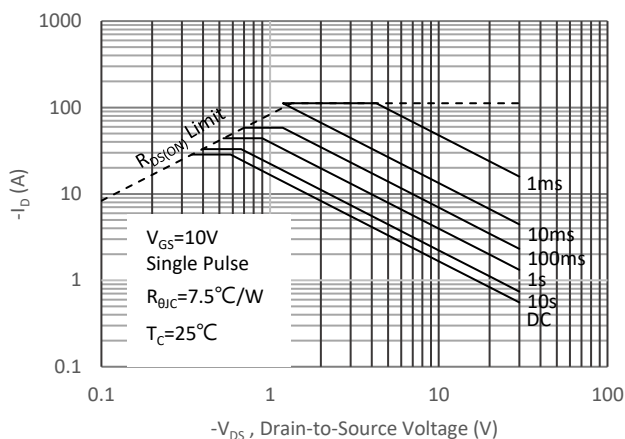


Fig 9. Maximum Safe Operating Area

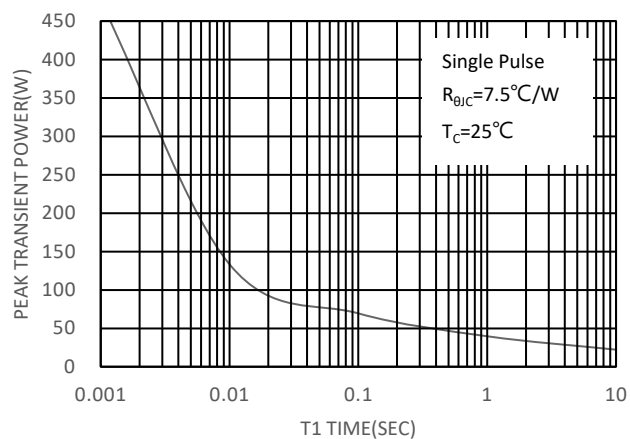


Fig 10. Single Pulse Maximum Power Dissipation

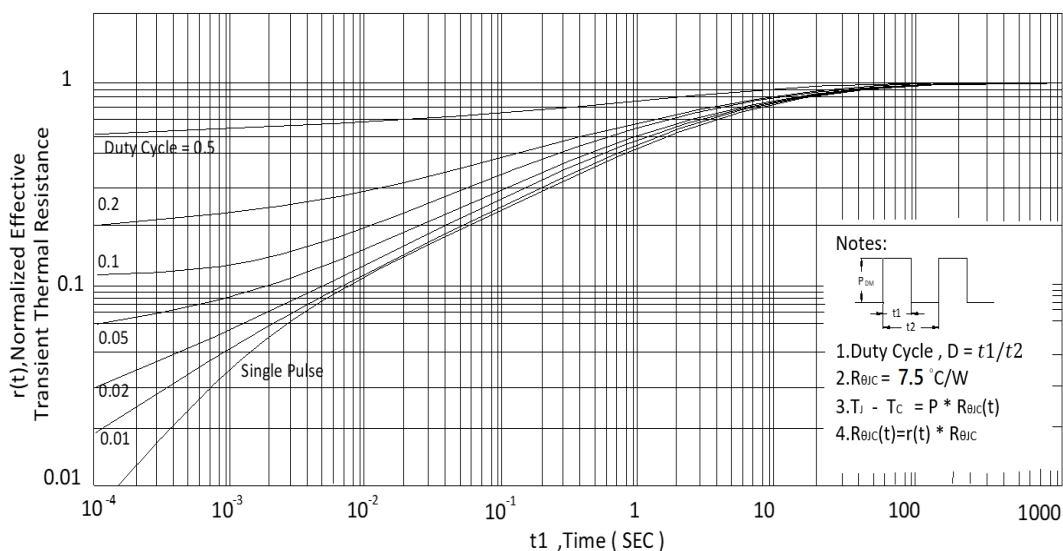


Fig 11. Effective Transient Thermal Impedance

Ordering & Marking Information:

Device Name: EMB15A03V for EDFN 3x3



B15A03: Device Name

ABCDEFGH: Date Code

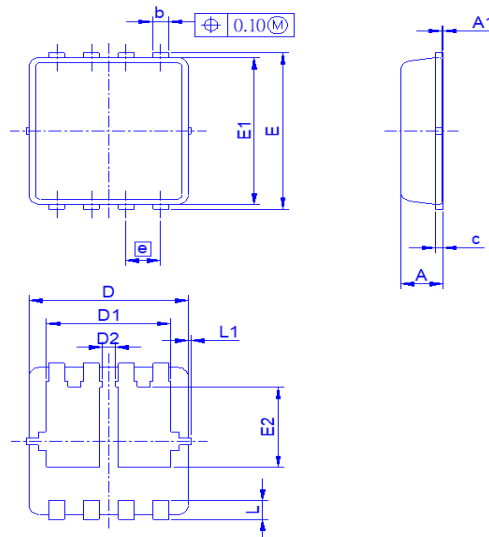
A: Assembly House

B: Year(A:2008 B:2009 C:2010....)

C: Month(A:01 B:02 C:03 D:04 E:05 F:06 G:07 H:08 I:09 J:10 K:11 L:12)

DEFG: Serial No.

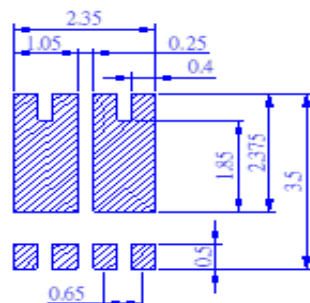
Outline Drawing



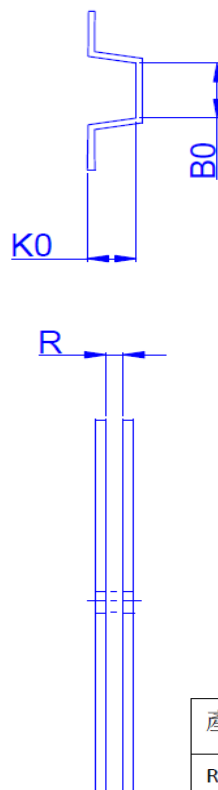
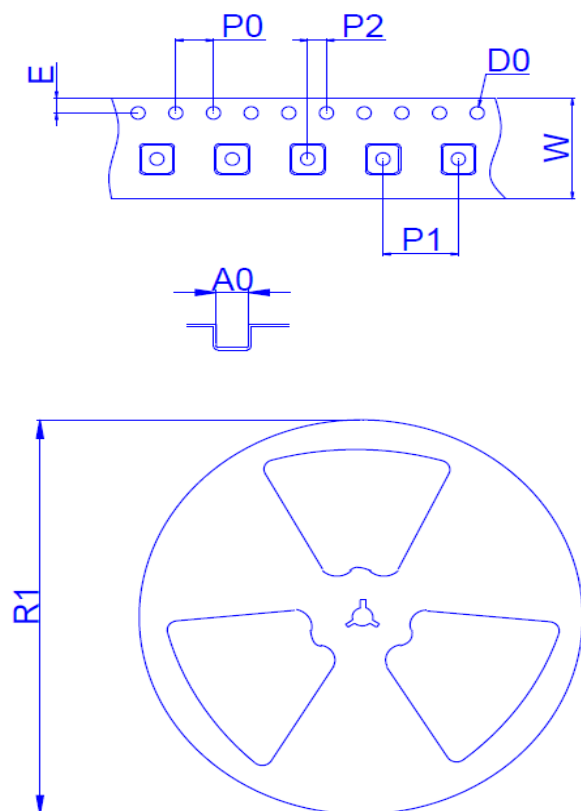
Dimension	A	A1	b	c	D	D1	D2	E	E1	E2	e	L
Min.	0.65	0	0.2	0.1	2.9	2.15	0.28	3.1	2.9	1.53	0.55	0.3
Typ.	0.75	-	0.3	0.15	3	2.47	0.38	3.2	3	1.81	0.65	0.4
Max.	0.9	0.05	0.4	0.25	3.3	2.75	-	3.5	3.3	1.98	0.75	0.5

Dimension	L1	θ1
Min.	-	0°
Typ.	0.075	10°
Max.	0.15	14°

Footprint



◆ **Tape&Reel Information:5000pcs/Reel**
(Dimension in millimeter)



產品別	EDFN3X3
Reel 尺寸	13"
編帶 方式	FEED DIRECTION

Dimension in mm

Dimension	Carrier tape									Reel	
	A0	B0	D0	E	K0	P0	P1	P2	W	R	R1
Typ.	3.6	3.5	1.55	1.7	1.2	4	8	2	12	14	330
±	0.3	0.3	0.2	0.2	0.2	0.1	0.1	0.1	1	2	2